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TANG(10) **Pub. No.: US 2022/0386472 A1**(43) **Pub. Date: Dec. 1, 2022**(54) **CIRCUIT BOARD PREPARATION METHOD**(71) Applicant: **SHENNAN CIRCUITS CO., LTD.**,
Shenzhen (CN)(72) Inventor: **Changsheng TANG**, Shenzhen (CN)(21) Appl. No.: **17/503,360**(22) Filed: **Oct. 18, 2021****Related U.S. Application Data**(63) Continuation of application No. PCT/CN2021/
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ABSTRACT

The main technical problem solved by the present disclosure is to provide a circuit board preparation method. The method includes: obtaining a to-be-processed plate comprising an insulating layer, a first copper layer, a second copper layer opposite to the first copper layer, a blind metalized hole, and a first tab facing the blind metalized hole; obtaining a white insulating material; laminating the white insulating material to a surface of the insulating layer, a surface of the first copper layer, a surface of the first tab, and a surface of the second copper layer to form a first white insulating medium layer and a second white insulating medium layer opposite to the first white insulating medium layer; and performing surface polishing for the first white insulating medium layer and grinding the first white insulating medium layer until the first tab is exposed to form a first white reflective layer.

A to-be-processed plate after film removal is obtained; wherein the to-be-processed plate comprises an insulating layer, a first copper layer arranged on a first surface of the insulating layer, a second copper layer arranged on a second surface of the insulating layer and opposite to the first copper layer, a blind metalized hole, and a first tab arranged on the first surface and facing the blind metalized hole.

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A white insulating material is obtained; the white insulating material is laminated to a surface of the insulating layer, a surface of the first copper layer, a surface of the first tab, and a surface of the second copper layer to form a first white insulating medium layer and a second white insulating medium layer on surfaces of the to-be-processed plate.

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The first white insulating medium layer is performed with surface polishing and grinded until the first tab is exposed to form a first white reflective layer.

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